MICROCHIP Semiconductor Device Type: CT / OT / OTY (C7X) 005 SOT-23 Matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
		"Contained In"	% I otal	1	r F					e3
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	12.77	(mg) Total	Mold Compound	% ot Total Weight	79.8
Silica, vitreous	60676-86-0	Mold Compound	69.354	11.097	693,542		Silica, vitreous	60676-86-0	86.91	
Epoxy Resin	Trade Secret	Mold Compound	6.121	0.979	61,207		Epoxy Resin	Trade Secret	7.67	
Phenolic Resin	Trade Secret	Mold Compound	4.078	0.652	40,778		Phenolic Resin	Trade Secret	5.11	
Carbon Black	1333-86-4	Mold Compound	0.247	0.040	2,474		Carbon Black	1333-86-4	0.31	
Copper	7440-50-8	Lead Frame	10.031	1.605	100,314			Total		
Iron	7439-89-6	Lead Frame	0.247	0.039	2,468	1.68	(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.200	0.032	2,000		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.013	0.002	131		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.009	0.001	87		Silver	7440-22-4	1.91	
Silver (Ag)	7440-22-4	Die Attach	0.563	0.090	5,625		Zinc	7440-66-6	0.13	
Modified Epoxy Resin	13561-08-5	Die Attach	0.105	0.017	1,050		Phosphorous	7723-14-0	0.08	
Diglycidylether of bisphenol-F	54208-63-8	Die Attach	0.056	0.009	563			Total	100.00	3
Modified Amine	827-43-0	Die Attach	0.026	0.004	263	0.12	(mg) Total	Die Attach	% of Total Weight	0.75
Silicon	7440-21-3	Chip (Die)	7.500	1.200	75.000		Silver (Ag)	7440-22-4	75.00	
Copper	7440-50-8	Wire Bond palladium coated copper (CuPd)	0.197	0.031	1,965		Modified Epoxy Resin	13561-08-5	14.00	
Palladium	7440-05-3	Wire Bond palladium coated copper (CuPd)	0.004	0.001	35		Dialvcidvlether of bisphenol-F	54208-63-8	7.50	
Tin		Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	0.200	12,500		Modified Amine	827-43-0	3.50	
1111	1440 01 0	TOTALS:	100.000	16.000	1,000,000		Modified Affilia	Total		
			100.000	10.000	1,000,000	1.20			% of Total Weight	
		g Total Mass				1.20	Total (mg)	Chip (Die)	% of rotal weight	7.5
5) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex	xemption (zero)	002/95/EC (27 January 2003) & Directive 2011/65/EU (08 J supplier declarations, and /or analytical test data.	une 2011) and	2015/863/EU (3	31 March		Doped Silicon	7440-21-3 Total	100.00 100.00	
15) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex ompliance with the above EU Directives has been verified a chemical substance is absent from the list above, the cl corporated's knowledge and belief as of the date of this d	xemption (zero) via internal design controls, s hemical substance is NOT an locument, there is no credible		o the best of Mi	crochip Techr	ology	0.03	Doped Silicon (mg) Total	Total Wire Bond - Copper, palladium		
15) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex impliance with the above EU Directives has been verified a chemical substance is absent from the list above, the cl corporated's knowledge and belief as of the date of this d t below the threshold of regulatory concern for any regul	xemption (zero) via internal design controls, - nemical substance is NOT an locument, there is no credible latory scheme world-wide.	supplier declarations, and /or analytical test data. intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentr	o the best of Mi ation of the ch	crochip Techn emical substa	ology	0.03	(mg) Total	Total Wire Bond - Copper, palladium coated (CuPd)	100.00 % of Total Weight	
15) and 2002/53/EC (End-of-Life Vehicles (ELV) without exampliance with the above EU Directives has been verified a chemical substance is absent from the list above, the cl corporated's knowledge and belief as of the date of this d t below the threshold of regulatory concern for any regul bolding compounds used by Microchip meet the UL94 V0 f	xemption (zero) via internal design controls, i nemical substance is NOT an locument, there is no credible latory scheme world-wide. lammability standard for plas	supplier declarations, and /or analytical test data.	o the best of Mi ation of the ch	crochip Techn emical substa	ology	0.03		Total Wire Bond - Copper, palladium	100.00	
15) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex- mpliance with the above EU Directives has been verified a chemical substance is absent from the list above, the cl corporated's knowledge and belief as of the date of this d t below the threshold of regulatory concern for any regul idding compounds used by Microchip meet the UL94 V0 f p/ul.com/global/eng/pages/offerings/industries/chemica e protective "tubes" in which the specific product is ship.	xemption (zero) via internal design controls, nemical substance is NOT an locument, there is no credible atory scheme world-wide. lammability standard for plas als/plastics/	supplier declarations, and /or analytical test data. intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentr	o the best of Mi ation of the ch obtain a test re	crochip Techr emical substar port at	nology nce, if any, is	0.03	(mg) Total	Total Wire Bond - Copper, palladium coated (CuPd)	100.00 % of Total Weight	
115) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex- ompliance with the above EU Directives has been verified a chemical substance is absent from the list above, the cl corporated's knowledge and belief as of the date of this do to below the threshold of regulatory concern for any regul olding compounds used by Microchip meet the UL94 V0 f tp://ul.com/global/eng/pages/offerings/industries/chemica ne protective "tubes" in which the specific product is ship ertain "reels" may be made from PVC plastic.	xemption (zero) via internal design controls, nemical substance is NOT an locument, there is no credible atory scheme world-wide. lammability standard for plas als/plastics/ upped are made from polyvinyl	supplier declarations, and /or analytical test data. intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentra- tics. You can access the UL iQTM family of databases to o	o the best of Mi ation of the ch obtain a test re the packing sl	crochip Techn emical substan port at ip on the oute	nology nce, if any, is r box and	0.03	(mg) Total Copper	Total Wire Bond - Copper, palladium coated (CuPd) 7440-50-8	100.00 % of Total Weight 98.25 1.75	
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